

Fig. 2

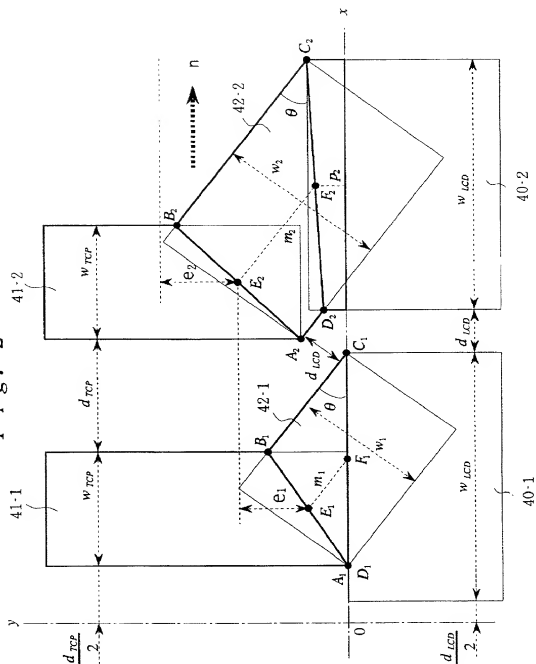
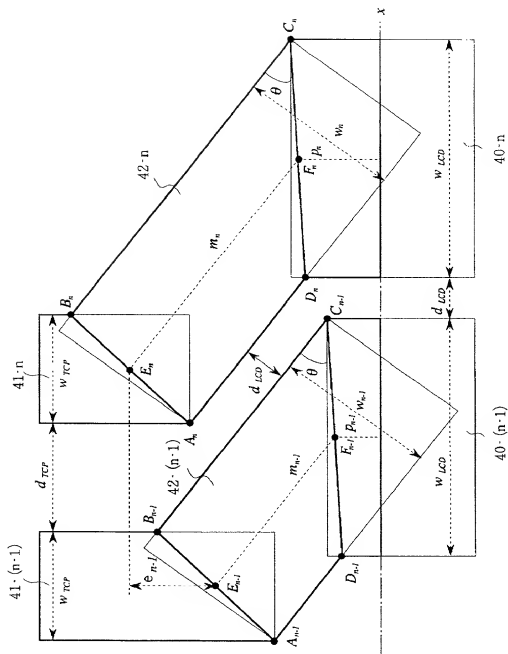
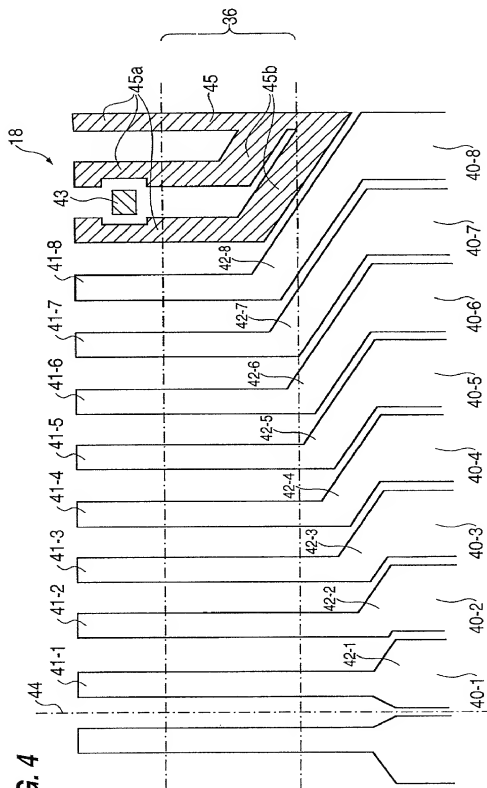


Fig. 3



44



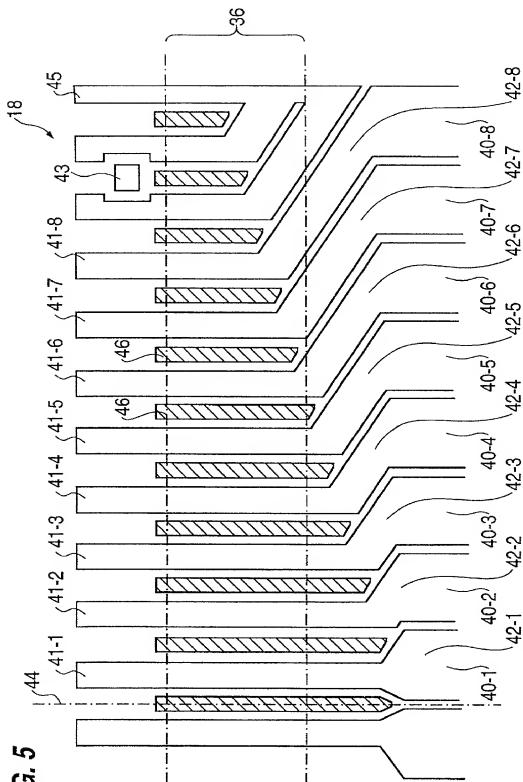


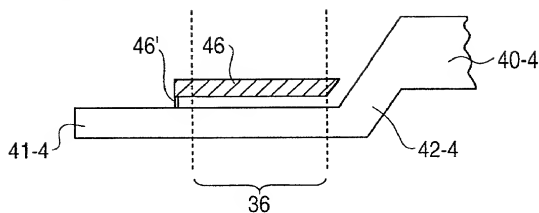
FIG. 6

FIG. 7A

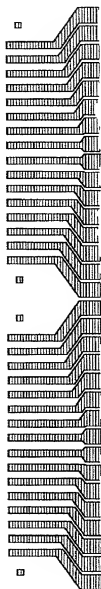


FIG. 7B

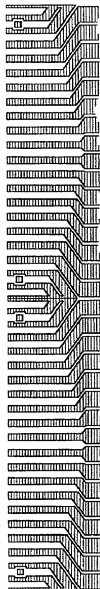


FIG. 7C

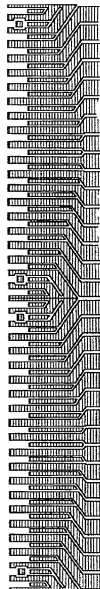


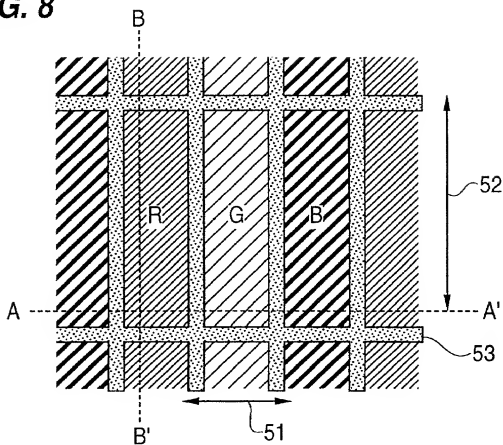
FIG. 8

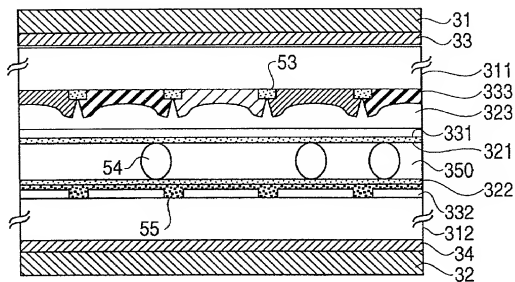
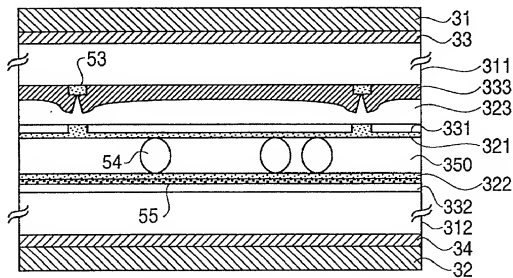
FIG. 9A**FIG. 9B**

FIG. 10

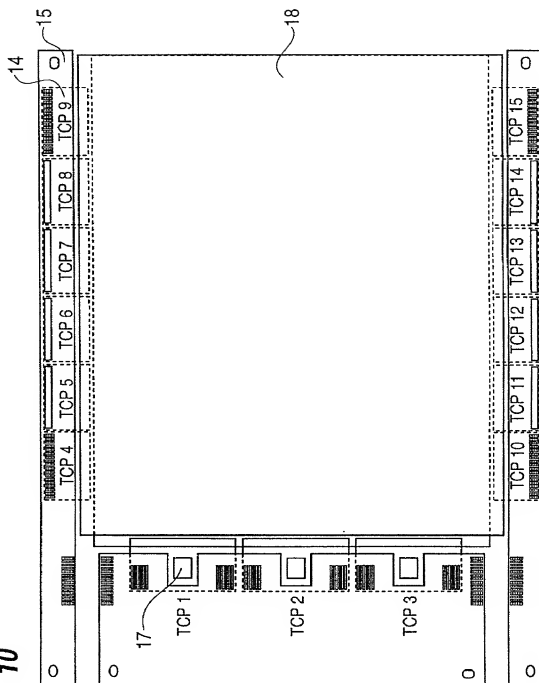


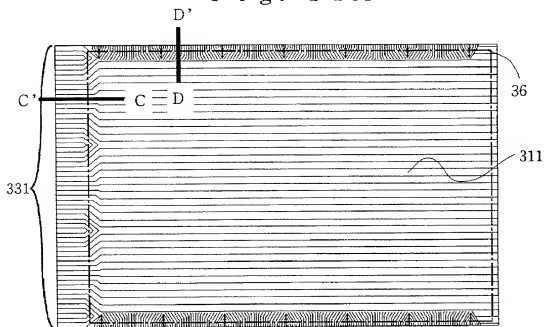
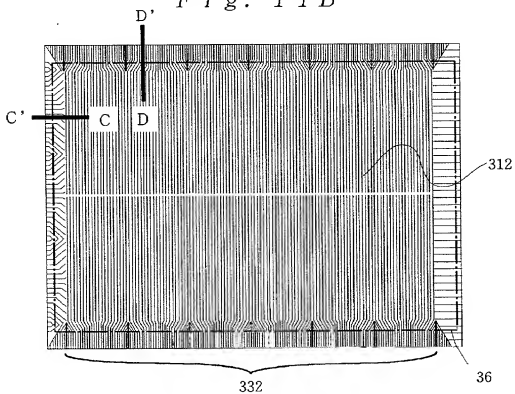
Fig. 11A*Fig. 11B*

FIG. 12B

FIG. 12B is a cross-sectional view of a device assembly. It shows a substrate 331 with a layer 70 on top. A circular feature 36 is on the left. To its right, a wavy line 79 indicates a transition. Further right, a layer 78 is shown with circular features 54. A vertical arrow points down between two layers. On the far right, a layer 77 is shown with circular features 54. A vertical arrow points up between two layers. The entire assembly is bounded by a top and bottom layer with diagonal hatching.

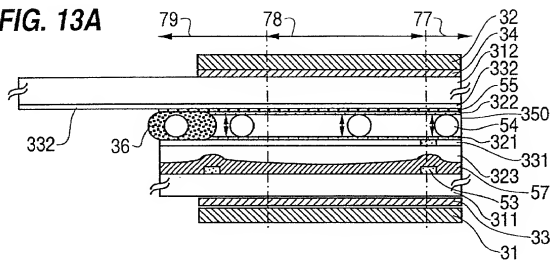
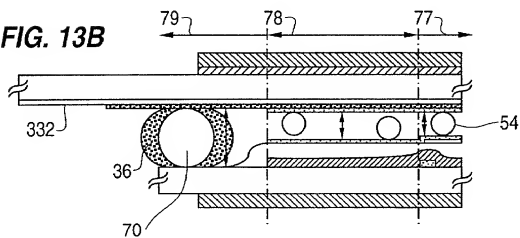
FIG. 13A**FIG. 13B**

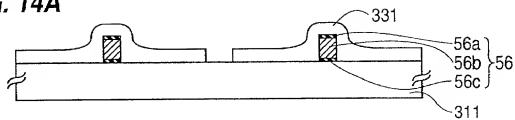
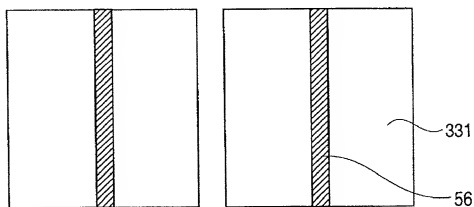
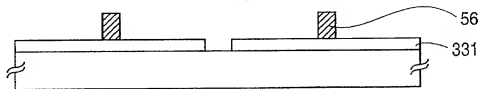
FIG. 14A**FIG. 14B****FIG. 14C**

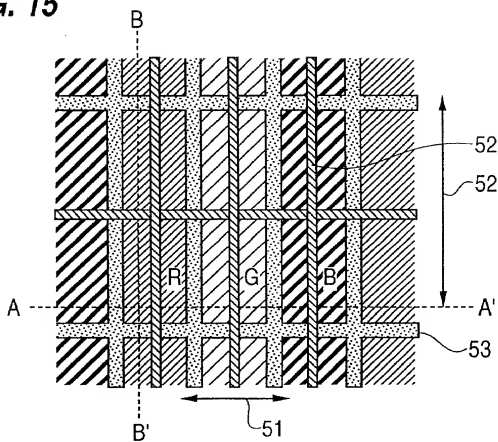
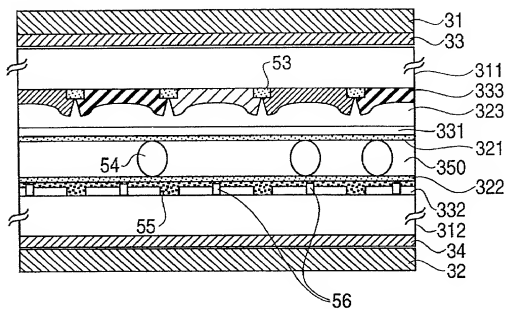
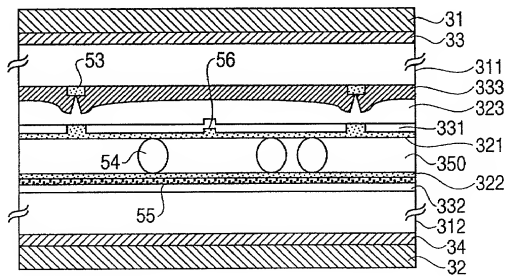
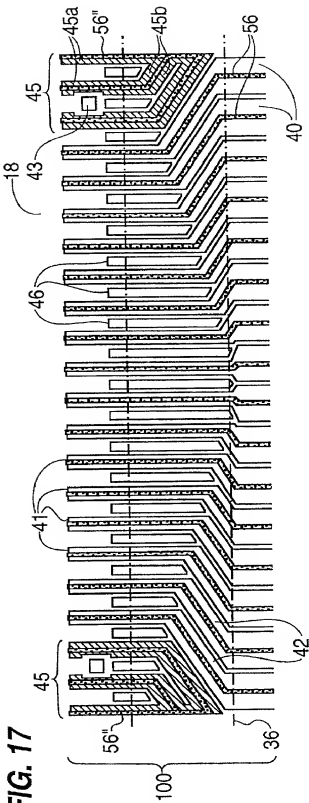
FIG. 15

FIG. 16A**FIG. 16B**



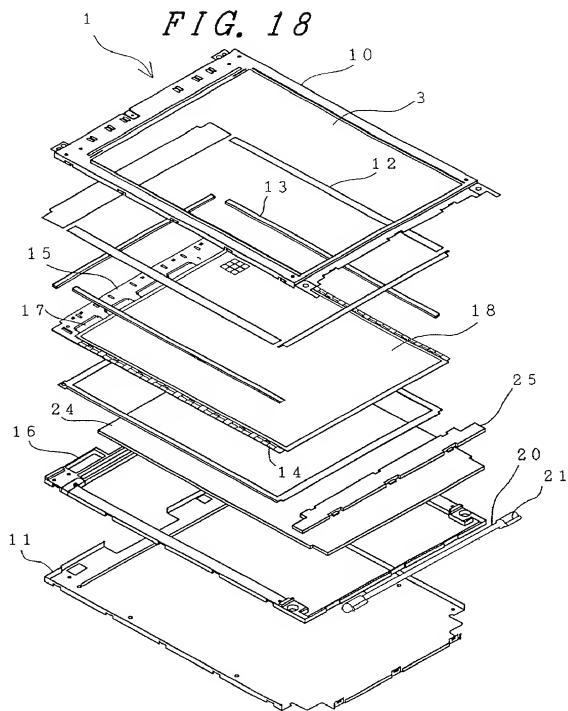


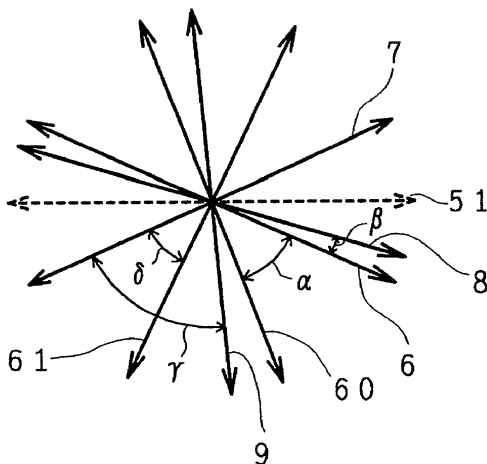
FIG. 19

FIG. 20

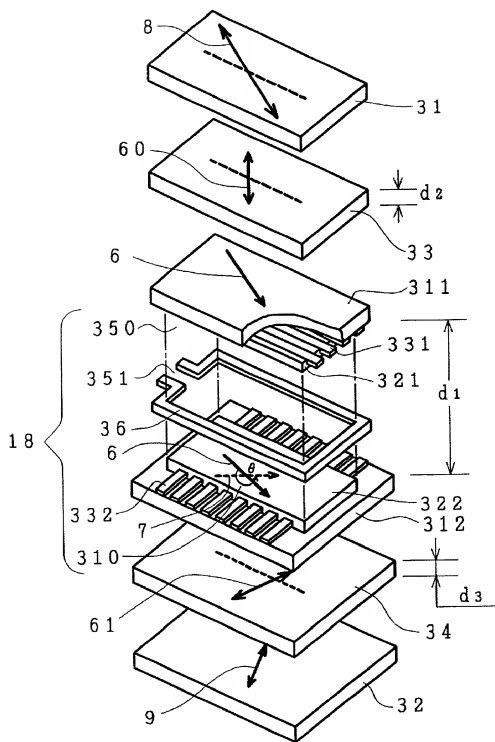


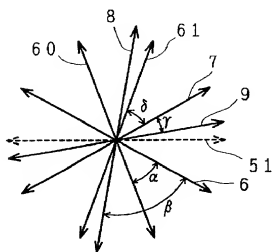
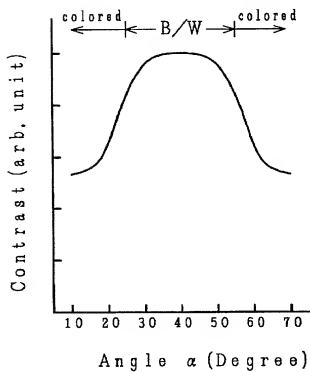
FIG. 21*FIG. 22*

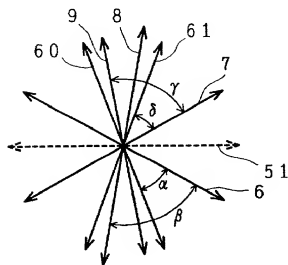
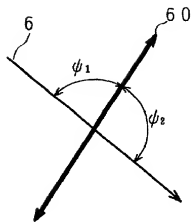
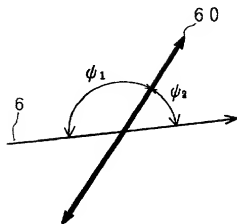
FIG. 23*FIG. 24A**FIG. 24B*

FIG. 25

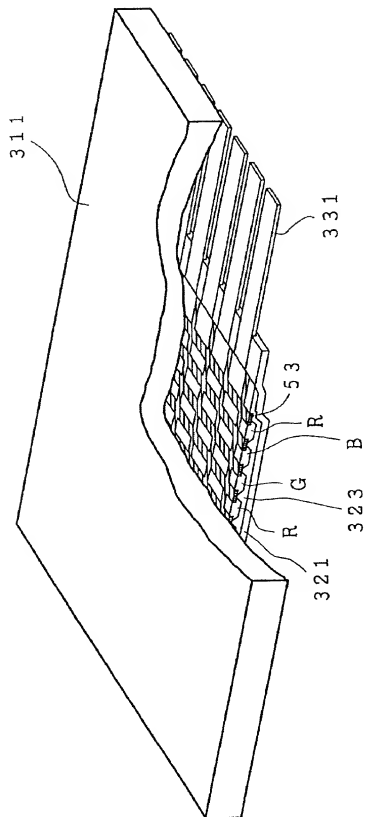
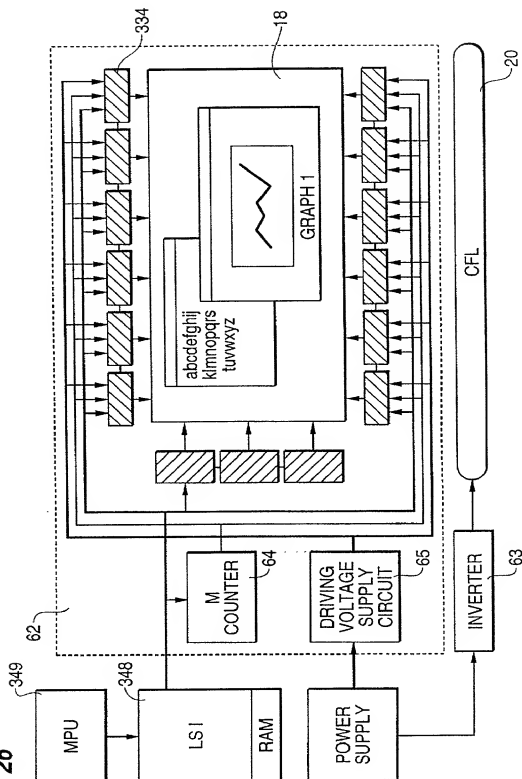


FIG. 26



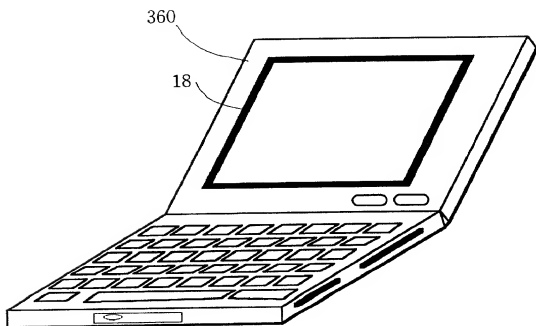
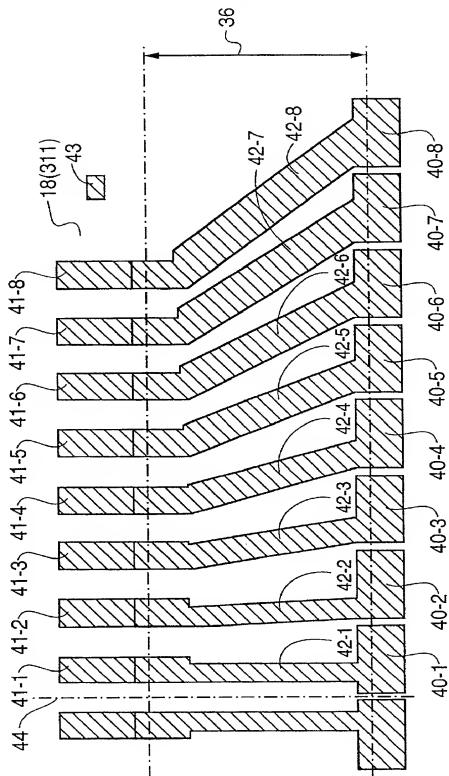
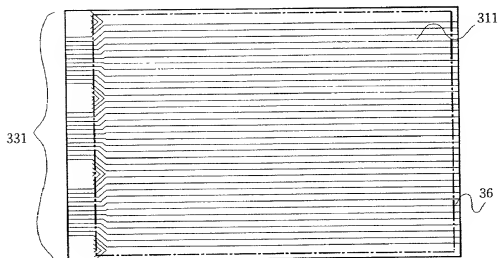
F i g . 2 7

FIG. 28
(PRIOR ART)

*Fig. 29A**Prior Art**Fig. 29B**Prior Art*